

Description

The RSD140P06 uses advanced trench technology

to provide excellent $R_{\,DS(ON)},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



General Features

 $V_{DS} = -60V, I_{D} = -20A$

 $R_{DS(ON)} < 58m\Omega$ @ $V_{GS}=-10V$

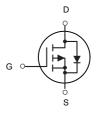
 $R_{DS(ON)}$ < 67m Ω @ V_{GS} =-4.5V

Application

PWM applications

Load switch

Power management



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
RSD140P06	TO-252-2L	HXY MOSFET	2500

ABSOLUTE MAXIMUM RATINGS(TA=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
VDS	Drain-Source Voltage	-60	V
VGS	Gate-Source Voltage	±20	V
I _D (25°C)		-20	А
I _D (70°C)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-12	А
IDM		-30	Α
PD	Maximum Power Dissipation	25	W
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	℃
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	65	°CM



ELECTRICAL CHARACTERISTICS (TA=25 °C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.023	-	V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-10A		48	58	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-6A		56	67	
V _{GS(th)}	Gate Threshold Voltage	V -V I - 2500A	-1.2		-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		4		mV/°C
	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	
I _{DSS}		V _{DS} =-24V , V _{GS} =0V , T _J =55°C	_S =0V , T _J =55°C5		-5	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-15A		12		S
Qg	Total Gate Charge (-4.5V)			6.1		nC
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-15A		3.1		
Q _{gd}	Gate-Drain Charge			1.8		
T _{d(on)}	Turn-On Delay Time			2.6		
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		8.6		ns
T _{d(off)}	Turn-Off Delay Time	I _D =-15A		33.6		
T _f	Fall Time			6		
C _{iss}	Input Capacitance			585		
C _{oss}	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		100		pF
C _{rss}	Reverse Transfer Capacitance			85		
Is	Continuous Source Current ^{1,5}	V V 0V 5 0			-20	Α
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			-30	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/µs ,		6.1		nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C		1.4		nC

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$

^{3.} The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH, I_{AS} =-19A

^{4.} The power dissipation is limited by 150°C junction temperature

^{5.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

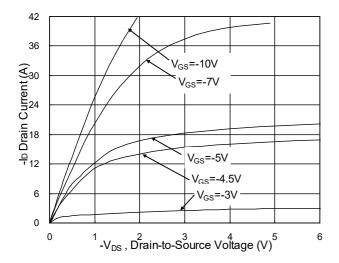


Fig.1 Typical Output Characteristics

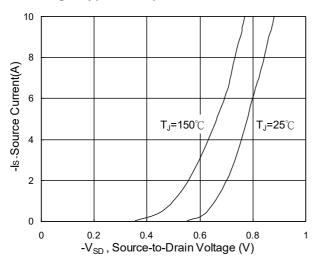


Fig.3 Forward Characteristics Of Reverse

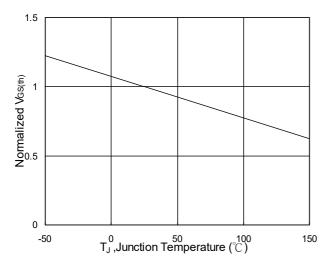


Fig.5 Normalized V_{GS(th)} vs. T_J

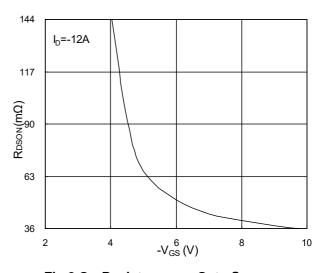


Fig.2 On-Resistance v.s Gate-Source

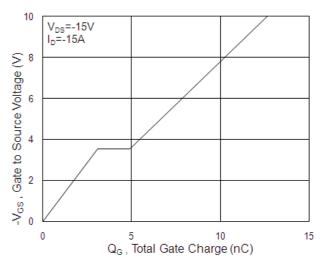


Fig.4 Gate Charge Characteristics

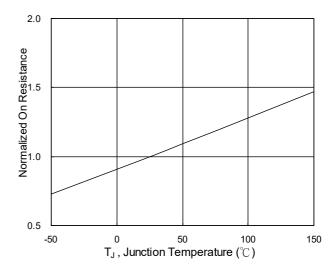
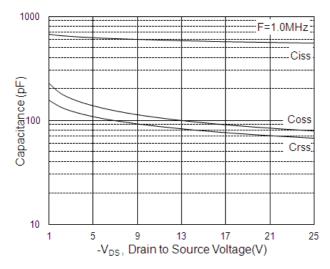


Fig.6 Normalized R_{DSON} vs. T_J



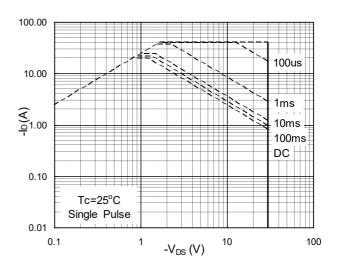


Fig.7 Capacitance

Fig.8 Safe Operating Area

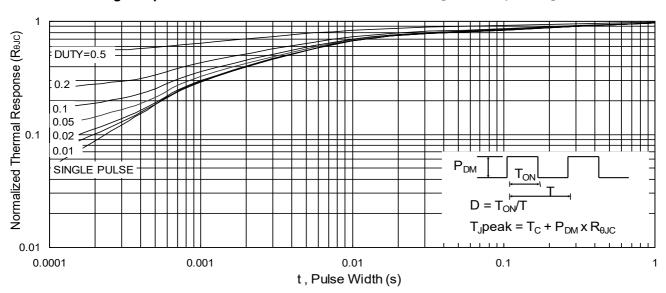


Fig.9 Normalized Maximum Transient Thermal Impedance

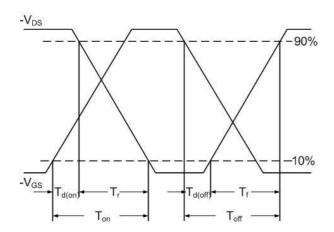


Fig.10 Switching Time Waveform

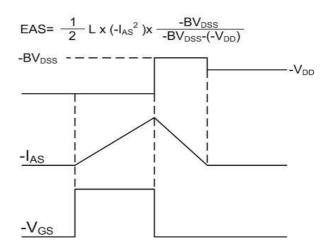
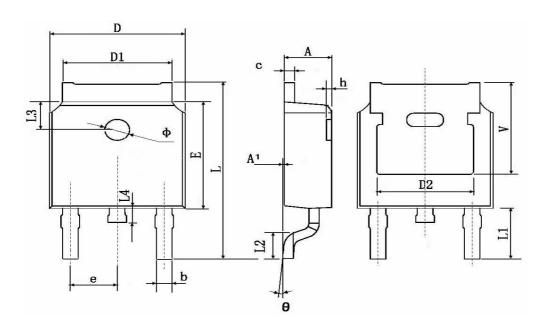


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min.	Max.	Min.	Max.		
Α	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
С	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	4.830 TYP.		0.190 TYP.			
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900 TYP.		0.114 TYP.			
L2	1.400	1.700	0.055	0.067		
L3		1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039		
Ф	1.100	1.300	0.043	0.051		
θ	0°	8°	0°	8°		
h	0.000	0.300	0.000	0.012		
V	5.350	0.211 TYP.		TYP.		



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